

Title (en)
SEMICONDUCTOR JOINING SUBSTRATE-USE TAPE WITH ADHESIVE AND COPPER-CLAD LAMINATE SHEET USING IT

Title (de)
SELBSTKLEBEBAND FÜR SUBSTRATE ZUR VERBINDUNG MIT HALBLEITERN UND KUPFERKASCHIERTES LAMINAT MIT DIESEM KLEBEBAND

Title (fr)
BANDE ADHESIVE DESTINEE A ETRE UTILISEE POUR UN SUBSTRAT DE CONNEXION DE SEMI-CONDUCTEURS ET FEUILLE STRATIFIEE REVETUE DE CUIVRE UTILISANT LADITE BANDE

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EP 1249863 A8 20030115 (EN)

Application
EP 01958398 A 20010822

Priority
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• JP 2000255352 A 20000825

Abstract (en)
[origin: EP1249863A1] Semiconductor-use tape with an adhesive comprises a laminate consisting of an insulating film layer having a linear expansion coefficient in a film width direction (TD) at 50-200[deg]C of 17-30 ppm/[deg]C and tensile modulus of elasticity of 6-12 Gpa, and at least one semi-cured adhesive layer. .

IPC 1-7
H01L 21/60

IPC 8 full level
H01L 21/60 (2006.01); **H01L 23/31** (2006.01); **H01L 23/495** (2006.01)

CPC (source: EP KR US)
H01L 21/60 (2021.08 - KR); **H01L 23/3114** (2013.01 - EP US); **H01L 23/3128** (2013.01 - EP US); **H01L 23/3185** (2013.01 - EP US); **H01L 23/49572** (2013.01 - EP US); **H01L 24/50** (2013.01 - EP US); **H01L 24/86** (2013.01 - EP US); **H01L 2224/16** (2013.01 - EP US); **H01L 2224/16245** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01027** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01045** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01077** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/351** (2013.01 - EP US); **Y10T 428/24843** (2015.01 - EP US); **Y10T 428/28** (2015.01 - EP US); **Y10T 428/2852** (2015.01 - EP US); **Y10T 428/287** (2015.01 - EP US)

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